XFRMR detils :

Primary - Secondary Ration 1-4:5-8 =1:15
Primary Peak Current = 2A
Primary RMS current = 0.5A
Secondary Peak Current= 0.130
Secondary RMS= 0.50mA
Primary Inductance=5uH
ER9.5S Core (N87/CF139)

BAT+
3.3V-5V
575-4
PWRGND
575-4
BAT-

220uF @6.3V electrolytic Cap was added at the input terminal for all the testing on the board

C4 22µF
C5 0.47µF
R1 24k 0.125W
C6 0.22µF
C1 2200pF 2000V
C2 2200pF 2000V
T1
PRI
SEC
750315627
D1 ES1G-13-F
D2 ES3AB-13-F
R2 41.2k
R5 45.3k
R4 4.7
Q1 CSD18504Q5A 40V
R6 1.30k
C12 100pF
R9 0.05
R3 200
C11 100pF 250V
C7 10µF
C10 0.1µF
120V @ 10mA
VOUT
575-4
575-4
ISO_GND

U1
LM3481MM
COMP
FB
FA/SYNC/SD
VCC
PGND
UVLO
VIN
DR
ISEN
AGND
R10 4.70k
R12 5.62k
C14 1000pF
C15 0.1µF
R13 162k
C16 0.22µF

U2
LTV-817S
R14 1.00k
R11 10.0k
D4 BAS16W-7-F
D5 BAS16W-7-F
C17 0.47µF
R15 5.62k
C13 0.01µF
D3 1SMB5932BT3G 20V
R7 42.2k
R8 0
R7 - Two 85K resistances were put in parallel for better thermal perfomenace during testing
R16 127k
C18 100pF
R17 56.2k
C19 0.1µF
U3
TL431AIDBZ
PRE
R18 2.74k

PWRGND
GND

Number: PMP10712	Rev: E1	Designed for: Public Release	Mod. Date: 8/12/2015
SVN Rev: Not in version control		Project Title: Low Vin FLyback Small form factor design for APD	
Drawn By:		Sheet Title:	
Engineer: Ambreesh Tripathi		Assembly Variant: [No Variations]	Sheet: 1 of 1
		File: PMP10712_Sch REV1.SchDoc	Size: B
		Contact: http://www.ti.com/support	

TEXAS INSTRUMENTS
http://www.ti.com

H1 NY PMS 440 0025 PH

H2 NY PMS 440 0025 PH

H3 NY PMS 440 0025 PH

H4 NY PMS 440 0025 PH

H5 1902C

H6 1902C

H7 1902C

H8 1902C

FID1

FID2

FID3

PCB Number: PMP10712
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
PMP10712

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Number: PMP10712	Rev: E1	Designed for: Public Release	Mod. Date: 6/25/2015
SVN Rev: Not in version control		Project Title: Low Vin FLyback Small form factor design for APD	
Drawn By:		Sheet Title:	
Engineer: Ambreesh Tripathi		Assembly Variant: [No Variations]	Sheet: 1 of 1
		File: PMP10712_Hardware.SchDoc	Size: B
		Contact: http://www.ti.com/support	http://www.ti.com

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